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**Understanding Embedded - CPLDs (Complex Programmable Logic Devices)** 

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

# **Applications of Embedded - CPLDs**

Details	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	1250
Number of I/O	52
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7064lc68-7yy

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest
- Programming support
  - Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices
  - The BitBlaster<sup>TM</sup> serial download cable, ByteBlasterMV<sup>TM</sup> parallel port download cable, and MasterBlaster<sup>TM</sup> serial/universal serial bus (USB) download cable program MAX 7000S devices

# General Description

The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2.* See Table 3 for available speed grades.

Device					Speed	l Grade				
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20
EPM7032		<b>✓</b>	<b>✓</b>		<b>✓</b>		<b>✓</b>	<b>✓</b>	<b>✓</b>	
EPM7032S	<b>✓</b>	<b>✓</b>	<b>✓</b>		<b>✓</b>					
EPM7064		<b>✓</b>	<b>✓</b>		~		<b>✓</b>	<b>✓</b>		
EPM7064S	<b>✓</b>	<b>✓</b>	<b>✓</b>		~					
EPM7096			<b>✓</b>		~		<b>✓</b>	<b>✓</b>		
EPM7128E			<b>✓</b>	<b>✓</b>	~		<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7128S		<b>✓</b>	<b>✓</b>		~			<b>✓</b>		
EPM7160E				<b>✓</b>	<b>✓</b>		<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7160S		<b>✓</b>	<b>✓</b>		~			<b>✓</b>		
EPM7192E						<b>✓</b>	<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7192S			<b>✓</b>		<b>✓</b>			<b>✓</b>		
EPM7256E						<b>✓</b>	<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7256S			<b>✓</b>		<b>✓</b>			<b>✓</b>		

The MAX 7000 architecture supports 100% TTL emulation and high-density integration of SSI, MSI, and LSI logic functions. The MAX 7000 architecture easily integrates multiple devices ranging from PALs, GALs, and 22V10s to MACH and pLSI devices. MAX 7000 devices are available in a wide range of packages, including PLCC, PGA, PQFP, RQFP, and TQFP packages. See Table 5.

Table 5. M.	AX 7000	) Maxim	um Use	r I/O Pii	ıs N	ote (1)						
Device	44- Pin PLCC	44- Pin PQFP	44- Pin TQFP	68- Pin PLCC	84- Pin PLCC	100- Pin PQFP	100- Pin TQFP	160- Pin PQFP	160- Pin PGA	192- Pin PGA	208- Pin PQFP	208- Pin RQFP
EPM7032	36	36	36									
EPM7032S	36		36									
EPM7064	36		36	52	68	68						
EPM7064S	36		36		68		68					
EPM7096				52	64	76						
EPM7128E					68	84		100				
EPM7128S					68	84	84 (2)	100				
EPM7160E					64	84		104				
EPM7160S					64		84 (2)	104				
EPM7192E								124	124			
EPM7192S								124				
EPM7256E								132 (2)		164		164
EPM7256S											164 (2)	164

#### Notes:

- When the JTAG interface in MAX 7000S devices is used for either boundary-scan testing or for ISP, four I/O pins become JTAG pins.
- (2) Perform a complete thermal analysis before committing a design to this device package. For more information, see the Operating Requirements for Altera Devices Data Sheet.

MAX 7000 devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000 architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

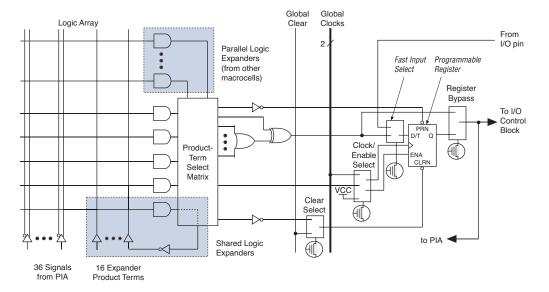
Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

## **Macrocells**

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell



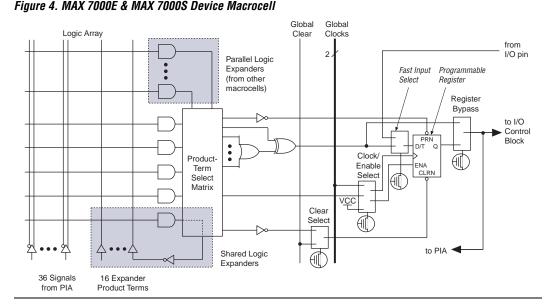


Figure 4 shows a MAX 7000E and MAX 7000S device macrocell.

Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register clear, preset, clock, and clock enable control functions. Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera development software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Each programmable register can be clocked in three different modes:

- By a global clock signal. This mode achieves the fastest clock-tooutput performance.
- By a global clock signal and enabled by an active-high clock enable. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- By an array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

In EPM7032, EPM7064, and EPM7096 devices, the global clock signal is available from a dedicated clock pin, GCLK1, as shown in Figure 1. In MAX 7000E and MAX 7000S devices, two global clock signals are available. As shown in Figure 2, these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in Figures 3 and 4, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear of the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in the device will be set to a low state.

All MAX 7000E and MAX 7000S I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be driven to an input D flipflop with an extremely fast (2.5 ns) input setup time.

# **Expander Product Terms**

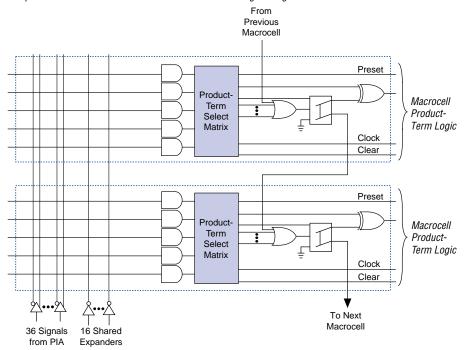
Although most logic functions can be implemented with the five product terms available in each macrocell, the more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources; however, the MAX 7000 architecture also allows both shareable and parallel expander product terms ("expanders") that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

The compiler can allocate up to three sets of up to five parallel expanders automatically to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay ( $t_{PEXP}$ ). For example, if a macrocell requires 14 product terms, the Compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms and the second set includes four product terms, increasing the total delay by  $2 \times t_{PEXP}$ .

Two groups of 8 macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lower-numbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of 8, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them. Figure 6 shows how parallel expanders can be borrowed from a neighboring macrocell.

Figure 6. Parallel Expanders

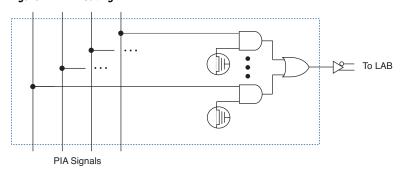
Unused product terms in a macrocell can be allocated to a neighboring macrocell.



# Programmable Interconnect Array

Logic is routed between LABs via the programmable interconnect array (PIA). This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000 dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 7 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input AND gate, which selects a PIA signal to drive into the LAB.

Figure 7. PIA Routing



While the routing delays of channel-based routing schemes in masked or FPGAs are cumulative, variable, and path-dependent, the MAX 7000 PIA has a fixed delay. The PIA thus eliminates skew between signals and makes timing performance easy to predict.

## I/O Control Blocks

The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or V<sub>CC</sub>. Figure 8 shows the I/O control block for the MAX 7000 family. The I/O control block of EPM7032, EPM7064, and EPM7096 devices has two global output enable signals that are driven by two dedicated active-low output enable pins (OE1 and OE2). The I/O control block of MAX 7000E and MAX 7000S devices has six global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.

When the tri-state buffer control is connected to ground, the output is tri-stated (high impedance) and the I/O pin can be used as a dedicated input. When the tri-state buffer control is connected to  $V_{CC}$ , the output is enabled.

The MAX 7000 architecture provides dual I/O feedback, in which macrocell and pin feedbacks are independent. When an I/O pin is configured as an input, the associated macrocell can be used for buried logic.

# In-System Programmability (ISP)

MAX 7000S devices are in-system programmable via an industry-standard 4-pin Joint Test Action Group (JTAG) interface (IEEE Std. 1149.1-1990). ISP allows quick, efficient iterations during design development and debugging cycles. The MAX 7000S architecture internally generates the high programming voltage required to program EEPROM cells, allowing in-system programming with only a single 5.0 V power supply. During in-system programming, the I/O pins are tri-stated and pulled-up to eliminate board conflicts. The pull-up value is nominally 50 k%.

ISP simplifies the manufacturing flow by allowing devices to be mounted on a printed circuit board with standard in-circuit test equipment before they are programmed. MAX 7000S devices can be programmed by downloading the information via in-circuit testers (ICT), embedded processors, or the Altera MasterBlaster, ByteBlasterMV, ByteBlaster, BitBlaster download cables. (The ByteBlaster cable is obsolete and is replaced by the ByteBlasterMV cable, which can program and configure 2.5-V, 3.3-V, and 5.0-V devices.) Programming the devices after they are placed on the board eliminates lead damage on high-pin-count packages (e.g., QFP packages) due to device handling and allows devices to be reprogrammed after a system has already shipped to the field. For example, product upgrades can be performed in the field via software or modem.

In-system programming can be accomplished with either an adaptive or constant algorithm. An adaptive algorithm reads information from the unit and adapts subsequent programming steps to achieve the fastest possible programming time for that unit. Because some in-circuit testers cannot support an adaptive algorithm, Altera offers devices tested with a constant algorithm. Devices tested to the constant algorithm have an "F" suffix in the ordering code.

The Jam<sup>TM</sup> Standard Test and Programming Language (STAPL) can be used to program MAX 7000S devices with in-circuit testers, PCs, or embedded processor.

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When  $V_{\rm CCIO}$  is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When  $V_{\rm CCIO}$  is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

### Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

# Programming with External Hardware

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.



For more information, see the *Altera Programming Hardware Data Sheet*.

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.



For more information, see the *Programming Hardware Manufacturers*.

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>IH</sub>	High-level input voltage		2.0	V <sub>CCINT</sub> + 0.5	V
V <sub>IL</sub>	Low-level input voltage		-0.5 (8)	0.8	V
V <sub>OH</sub>	5.0-V high-level TTL output voltage	I <sub>OH</sub> = -4 mA DC, V <sub>CCIO</sub> = 4.75 V (10)	2.4		V
	3.3-V high-level TTL output voltage	I <sub>OH</sub> = -4 mA DC, V <sub>CCIO</sub> = 3.00 V (10)	2.4		V
	3.3-V high-level CMOS output voltage	$I_{OH} = -0.1 \text{ mA DC}, V_{CCIO} = 3.0 \text{ V} (10)$	V <sub>CCIO</sub> - 0.2		V
V <sub>OL</sub>	5.0-V low-level TTL output voltage	I <sub>OL</sub> = 12 mA DC, V <sub>CCIO</sub> = 4.75 V (11)		0.45	V
	3.3-V low-level TTL output voltage	I <sub>OL</sub> = 12 mA DC, V <sub>CCIO</sub> = 3.00 V (11)		0.45	V
	3.3-V low-level CMOS output voltage	$I_{OL} = 0.1 \text{ mA DC}, V_{CCIO} = 3.0 \text{ V}(11)$		0.2	V
lı	Leakage current of dedicated input pins	$V_I = -0.5 \text{ to } 5.5 \text{ V } (11)$	-10	10	μА
l <sub>OZ</sub>	I/O pin tri-state output off-state current	$V_I = -0.5 \text{ to } 5.5 \text{ V } (11), (12)$	-40	40	μА

Table 1	6. MAX 7000 5.0-V Device Capa	ncitance: EPM7032, EPM7064 & EPM7	7096 Devices	Note (1	3)
Symbol	Parameter	Conditions	Min	Max	Unit
C <sub>IN</sub>	Input pin capacitance	V <sub>IN</sub> = 0 V, f = 1.0 MHz		12	pF
C <sub>I/O</sub>	I/O pin capacitance	V <sub>OUT</sub> = 0 V, f = 1.0 MHz		12	pF

Table 1	7. MAX 7000 5.0-V Device Capa	acitance: MAX 7000E Devices Note	(13)		
Symbol	Parameter	Conditions	Min	Max	Unit
C <sub>IN</sub>	Input pin capacitance	V <sub>IN</sub> = 0 V, f = 1.0 MHz		15	pF
C <sub>I/O</sub>	I/O pin capacitance	V <sub>OUT</sub> = 0 V, f = 1.0 MHz		15	pF

Table 1	8. MAX 7000 5.0-V Device Capa	acitance: MAX 7000S Devices Note	(13)		
Symbol	Parameter	Conditions	Min	Max	Unit
C <sub>IN</sub>	Dedicated input pin capacitance	V <sub>IN</sub> = 0 V, f = 1.0 MHz		10	pF
C <sub>I/O</sub>	I/O pin capacitance	V <sub>OUT</sub> = 0 V, f = 1.0 MHz		10	pF

#### Notes to tables:

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- (2) Minimum DC input voltage on I/O pins is –0.5 V and on 4 dedicated input pins is –0.3 V. During transitions, the inputs may undershoot to –2.0 V or overshoot to 7.0 V for input currents less than 100 mA and periods shorter than 20 ns.
- (3) Numbers in parentheses are for industrial-temperature-range devices.
- (4)  $V_{CC}$  must rise monotonically.
- (5) The POR time for all 7000S devices does not exceed 300 μs. The sufficient V<sub>CCINT</sub> voltage level for POR is 4.5 V. The device is fully initialized within the POR time after V<sub>CCINT</sub> reaches the sufficient POR voltage level.
- (6) 3.3-V I/O operation is not available for 44-pin packages.
- (7) The V<sub>CCISP</sub> parameter applies only to MAX 7000S devices.
- (8) During in-system programming, the minimum DC input voltage is –0.3 V.
- (9) These values are specified under the MAX 7000 recommended operating conditions in Table 14 on page 26.
- (10) The parameter is measured with 50% of the outputs each sourcing the specified current. The I<sub>OH</sub> parameter refers to high-level TTL or CMOS output current.
- (11) The parameter is measured with 50% of the outputs each sinking the specified current. The I<sub>OL</sub> parameter refers to low-level TTL, PCI, or CMOS output current.
- (12) When the JTAG interface is enabled in MAX 7000S devices, the input leakage current on the JTAG pins is typically -60 uA.
- (13) Capacitance is measured at 25° C and is sample-tested only. The OE1 pin has a maximum capacitance of 20 pF.

Figure 11 shows the typical output drive characteristics of MAX 7000 devices.

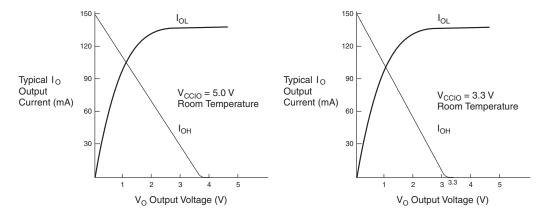


Figure 11. Output Drive Characteristics of 5.0-V MAX 7000 Devices

# **Timing Model**

MAX 7000 device timing can be analyzed with the Altera software, with a variety of popular industry-standard EDA simulators and timing analyzers, or with the timing model shown in Figure 12. MAX 7000 devices have fixed internal delays that enable the designer to determine the worst-case timing of any design. The Altera software provides timing simulation, point-to-point delay prediction, and detailed timing analysis for a device-wide performance evaluation.

Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	OE (-10P)		00 (-10) DOE (-10)	
			Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			0.5		1.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.5		1.0	ns
t <sub>FIN</sub>	Fast input delay	(2)		1.0		1.0	ns
t <sub>SEXP</sub>	Shared expander delay			5.0		5.0	ns
t <sub>PEXP</sub>	Parallel expander delay			0.8		0.8	ns
$t_{LAD}$	Logic array delay			5.0		5.0	ns
t <sub>LAC</sub>	Logic control array delay			5.0		5.0	ns
t <sub>IOE</sub>	Internal output enable delay	(2)		2.0		2.0	ns
t <sub>OD1</sub>	Output buffer and pad delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		1.5		2.0	ns
t <sub>OD2</sub>	Output buffer and pad delay Slow slew rate = off V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		2.0		2.5	ns
t <sub>OD3</sub>	Output buffer and pad delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.5		6.0	ns
t <sub>ZX1</sub>	Output buffer enable delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		5.0		5.0	ns
t <sub>ZX2</sub>	Output buffer enable delay Slow slew rate = off V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		5.5		5.5	ns
t <sub>ZX3</sub>	Output buffer enable delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns
$t_{SU}$	Register setup time		2.0		3.0		ns
$t_H$	Register hold time		3.0		3.0		ns
t <sub>FSU</sub>	Register setup time of fast input	(2)	3.0		3.0		ns
$t_{FH}$	Register hold time of fast input	(2)	0.5		0.5		ns
$t_{RD}$	Register delay			2.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			2.0		1.0	ns
t <sub>IC</sub>	Array clock delay			5.0		5.0	ns
$t_{EN}$	Register enable time			5.0		5.0	ns
t <sub>GLOB</sub>	Global control delay			1.0		1.0	ns
t <sub>PRE</sub>	Register preset time			3.0		3.0	ns
t <sub>CLR</sub>	Register clear time			3.0		3.0	ns
t <sub>PIA</sub>	PIA delay			1.0		1.0	ns
t <sub>LPA</sub>	Low-power adder	(8)		11.0		11.0	ns

Table 2	5. MAX 7000 & MAX 7000E	External Timing I	Paramete	ers /	lote (1)				
Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	15	-1	5T	-2	20	
			Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>SU</sub>	Global clock setup time		11.0		11.0		12.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input	(2)	3.0		-		5.0		ns
t <sub>FH</sub>	Global clock hold time of fast input	(2)	0.0		-		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		8.0		8.0		12.0	ns
t <sub>CH</sub>	Global clock high time		5.0		6.0		6.0		ns
t <sub>CL</sub>	Global clock low time		5.0		6.0		6.0		ns
t <sub>ASU</sub>	Array clock setup time		4.0		4.0		5.0		ns
t <sub>AH</sub>	Array clock hold time		4.0		4.0		5.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>ACH</sub>	Array clock high time		6.0		6.5		8.0		ns
t <sub>ACL</sub>	Array clock low time		6.0		6.5		8.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	6.0		6.5		8.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			13.0		13.0		16.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(5)	76.9		76.9		62.5		MHz
t <sub>ACNT</sub>	Minimum array clock period			13.0		13.0		16.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(5)	76.9		76.9		62.5		MHz
f <sub>MAX</sub>	Maximum clock frequency	(6)	100		83.3	_	83.3	_	MHz

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	15	-1	5T	-2	20	
			Min	Max	Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			2.0		2.0		3.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			2.0		2.0		3.0	ns
t <sub>FIN</sub>	Fast input delay	(2)		2.0		_		4.0	ns
t <sub>SEXP</sub>	Shared expander delay			8.0		10.0		9.0	ns
t <sub>PEXP</sub>	Parallel expander delay			1.0		1.0		2.0	ns
t <sub>LAD</sub>	Logic array delay			6.0		6.0		8.0	ns
t <sub>LAC</sub>	Logic control array delay			6.0		6.0		8.0	ns
t <sub>IOE</sub>	Internal output enable delay	(2)		3.0		_		4.0	ns
t <sub>OD1</sub>	Output buffer and pad delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		4.0		4.0		5.0	ns
t <sub>OD2</sub>	Output buffer and pad delay Slow slew rate = off V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		5.0		-		6.0	ns
t <sub>OD3</sub>	Output buffer and pad delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		8.0		-		9.0	ns
t <sub>ZX1</sub>	Output buffer enable delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		6.0		6.0		10.0	ns
t <sub>ZX2</sub>	Output buffer enable delay Slow slew rate = off V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		7.0		-		11.0	ns
t <sub>ZX3</sub>	Output buffer enable delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		10.0		-		14.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		6.0		6.0		10.0	ns
t <sub>SU</sub>	Register setup time		4.0		4.0		4.0		ns
t <sub>H</sub>	Register hold time		4.0		4.0		5.0		ns
t <sub>FSU</sub>	Register setup time of fast input	(2)	2.0		-		4.0		ns
t <sub>FH</sub>	Register hold time of fast input	(2)	2.0		-		3.0		ns
t <sub>RD</sub>	Register delay			1.0		1.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			1.0		1.0		1.0	ns
t <sub>IC</sub>	Array clock delay			6.0		6.0		8.0	ns
t <sub>EN</sub>	Register enable time			6.0		6.0		8.0	ns
t <sub>GLOB</sub>	Global control delay			1.0		1.0		3.0	ns
t <sub>PRE</sub>	Register preset time			4.0		4.0		4.0	ns
t <sub>CLR</sub>	Register clear time			4.0		4.0		4.0	ns
t <sub>PIA</sub>	PIA delay			2.0		2.0		3.0	ns
t <sub>LPA</sub>	Low-power adder	(8)		13.0		15.0		15.0	ns

#### Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- This minimum pulse width for preset and clear applies for both global clear and array controls. The  $t_{LPA}$  parameter must be added to this minimum width if the clear or reset signal incorporates the  $t_{LAD}$  parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (7) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPPW}$  parameters for macrocells running in the low-power mode.

Tables 27 and 28 show the EPM7032S AC operating conditions.

Table 2	77. EPM7032\$ External Time	ing Parameter	s (Part	1 of 2	<b>)</b> No	ote (1)					
Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	5	-	6	-	7	-1	10	
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t <sub>SU</sub>	Global clock setup time		2.9		4.0		5.0		7.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns
t <sub>CH</sub>	Global clock high time		2.0		2.5		3.0		4.0		ns
t <sub>CL</sub>	Global clock low time		2.0		2.5		3.0		4.0		ns
t <sub>ASU</sub>	Array clock setup time		0.7		0.9		1.1		2.0		ns
t <sub>AH</sub>	Array clock hold time		1.8		2.1		2.7		3.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns
t <sub>ACH</sub>	Array clock high time		2.5		2.5		3.0		4.0		ns
t <sub>ACL</sub>	Array clock low time		2.5		2.5		3.0		4.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			5.7		7.0		8.6		10.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
t <sub>ACNT</sub>	Minimum array clock period			5.7		7.0		8.6		10.0	ns

#### Notes to tables:

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t<sub>LPA</sub> parameter must be added to this minimum width if the clear or reset signal incorporates the t<sub>LAD</sub> parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $\mathbf{t_{ACL}}$ , and  $\mathbf{t_{CPPW}}$  parameters for macrocells running in the low-power mode.

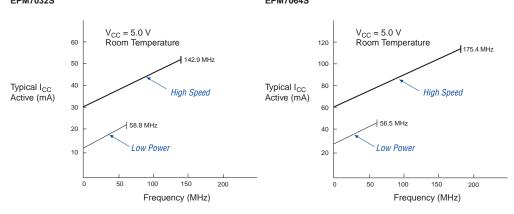
Tables 33 and 34 show the EPM7160S AC operating conditions.

Table 3	33. EPM7160S External Timi	ng Parameters	(Part	1 of 2)	No	nte (1)					
Symbol	Parameter	Conditions				Speed	Grade	)			Unit
			-	6	-	7	-1	0	-1	15	
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t <sub>SU</sub>	Global clock setup time		3.4		4.2		7.0		11.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.5		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		3.9		4.8		5		8	ns
t <sub>CH</sub>	Global clock high time		3.0		3.0		4.0		5.0		ns
t <sub>CL</sub>	Global clock low time		3.0		3.0		4.0		5.0		ns
t <sub>ASU</sub>	Array clock setup time		0.9		1.1		2.0		4.0		ns
t <sub>AH</sub>	Array clock hold time		1.7		2.1		3.0		4.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		6.4		7.9		10.0		15.0	ns
t <sub>ACH</sub>	Array clock high time		3.0		3.0		4.0		6.0		ns
t <sub>ACL</sub>	Array clock low time		3.0		3.0		4.0		6.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	2.5		3.0		4.0		6.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			6.7		8.2		10.0		13.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	149.3		122.0		100.0		76.9		MHz

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			0.3		0.5		2.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.3		0.5		2.0	ns
t <sub>FIN</sub>	Fast input delay			3.4		1.0		2.0	ns
t <sub>SEXP</sub>	Shared expander delay			3.9		5.0		8.0	ns
$t_{PEXP}$	Parallel expander delay			1.1		0.8		1.0	ns
$t_{LAD}$	Logic array delay			2.6		5.0		6.0	ns
t <sub>LAC</sub>	Logic control array delay			2.6		5.0		6.0	ns
t <sub>IOE</sub>	Internal output enable delay			0.8		2.0		3.0	ns
t <sub>OD1</sub>	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns
t <sub>OD2</sub>	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns
t <sub>OD3</sub>	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		8.0	ns
t <sub>ZX1</sub>	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns
t <sub>ZX2</sub>	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns
t <sub>ZX3</sub>	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns
t <sub>SU</sub>	Register setup time		1.1		2.0		4.0		ns
t <sub>H</sub>	Register hold time		1.6		3.0		4.0		ns
t <sub>FSU</sub>	Register setup time of fast input		2.4		3.0		2.0		ns
t <sub>FH</sub>	Register hold time of fast input		0.6		0.5		1.0		ns
$t_{RD}$	Register delay			1.1		2.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			1.1		2.0		1.0	ns
t <sub>IC</sub>	Array clock delay			2.9		5.0		6.0	ns
$t_{EN}$	Register enable time			2.6		5.0		6.0	ns
t <sub>GLOB</sub>	Global control delay			2.8		1.0		1.0	ns
t <sub>PRE</sub>	Register preset time			2.7		3.0		4.0	ns
t <sub>CLR</sub>	Register clear time			2.7		3.0		4.0	ns
t <sub>PIA</sub>	PIA delay	(7)		3.0		1.0		2.0	ns
t <sub>LPA</sub>	Low-power adder	(8)		10.0	İ	11.0		13.0	ns

Figure 15 shows typical supply current versus frequency for MAX 7000S devices.





### EPM7128S EPM7160S

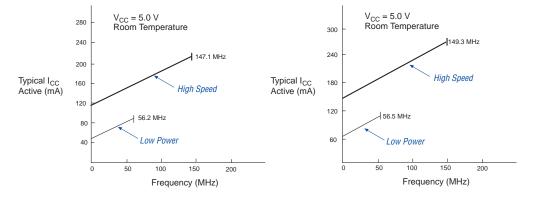
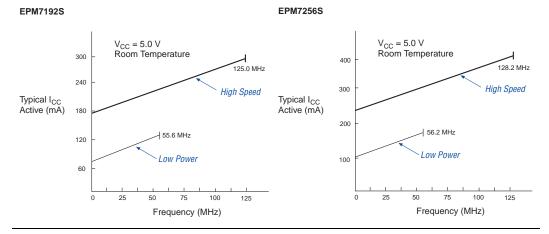


Figure 15. I<sub>CC</sub> vs. Frequency for MAX 7000S Devices (Part 2 of 2)



# Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.

# Revision History

The information contained in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7 supersedes information published in previous versions. The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7:

## Version 6.7

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.7:

Reference to AN 88: Using the Jam Language for ISP & ICR via an Embedded Processor has been replaced by AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

# Version 6.6

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.6:

- Added Tables 6 through 8.
- Added "Programming Sequence" section on page 17 and "Programming Times" section on page 18.

# Version 6.5

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.5:

Updated text on page 16.

## Version 6.4

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.4:

Added Note (5) on page 28.

## Version 6.3

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.3:

■ Updated the "Open-Drain Output Option (MAX 7000S Devices Only)" section on page 20.